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Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) Device A device for cooling power electronics (9), comprising:

a support plate (21) on which the power electronics are mounted, said support plate comprising at least one orifice,

a first pressed metal plate including liquid circulation channels press-formed in said

first pressed metal plate, said channels defining at least partially a cooling circuit for cooling

the power electronics by circulation of a liquid in the channels;

an intermediate plate sandwiched between said support plate and said pressed metal plate; and

at least one manifold fixed to the intermediate plate and connected to the cooling circuit, said at least one manifold being introduced in said at least one orifice of the support plate.

wherein a cooling circuit (22) for cooling by circulation of a liquid is defined by said liquid circulation channels mounted directly or indirectly to the support plate, and

wherein the first pressed metal plate is smaller than the support plate when observed in a direction perpendicular to said plates.

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- 2. (Currently amended) Cooling The cooling device according to claim 1, wherein the cooling circuit (22) comprises a liquid inlet channel (29), a liquid outlet channel (30) and said circulation channels (28) for the circulation of the liquid between the inlet channel and the outlet channel.
- 3. (Currently amended) Cooling The cooling device according to claim 2, wherein the cooling circuit comprises deflectors (31) situated in the liquid circulation channels.
- 4. (Currently amended) Cooling The cooling device according to claim 2, wherein the cooling circuit comprises turbulators (32) distributed in the liquid circulation channels.
 - 5. (Canceled)
 - 6. (Canceled)
 - 7. (Canceled)
 - 8. (Canceled)
- 9. (Currently amended) Cooling The cooling device according to claim 1, further comprising a metal wherein the manifold (27) connected to the cooling circuit is made of

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metal.

- 10. (Currently amended) Cooling The cooling device according to claim 1, wherein the first pressed metal plate is made of aluminum.
 - 11. (Canceled)
- 12. (Currently amended) Cooling The cooling device according to claim 1, wherein the pressed metal plate (23) is fixed directly by brazing to the support plate (21) intermediate plate.
- 13. (Currently amended) Cooling The cooling device according to claim 12, wherein at least one of the pressed metal plate (23) and the support plate (21) intermediate plate comprises plating by co-lamination.
- 14. (Currently amended) Cooling The cooling device according to claim 13, wherein the pressed and support plates (21, 23) metal plate and the intermediate plate are made from aluminum.
- 15. (Currently amended) Cooling The cooling device according to claim 9 1, wherein the support plate (21) intermediate plate carries the manifold.

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- 16. (Currently amended) Method A method of manufacturing a power electronics cooling device, comprising the steps of:
- producing a cooling circuit (22) by pressing a first metal plate (23) to integrally and homogenously form liquid circulation channels (28) in said first pressed metal plate,
- providing producing at least-one orifice through the first metal plate (23) and a support plate on which the power electronics are mounted, the support plate having at least one orifice,
 - -brazing the cooling circuit on-said support plate (21) for the power electronics (9),
- brazing, on the cooling circuit, at least one manifold (27) for a cooling liquid to provide a closed-loop fluid path connected to and delivering said cooling liquid to the manifold (27)
 - brazing at least one manifold on an intermediate plate.
- mounting the support plate on the intermediate plate such that the manifold on the intermediate plate is introduced in the orifice of the support plate, and
- mounting the intermediate plate on the pressed metal plate such that the manifold is connected to the cooling circuit.
 - 17. (Canceled)
 - 18. (Currently amended) Method The method according to claim 16, wherein the

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step of producing the cooling circuit by pressing of the first metal plate (23) comprises the pressing of deflectors (31) and/or turbulators (32) into the first metal plate (23).

- 19. (Currently amended) Alternator An alternator or alternator/starter for a motor vehicle, comprising a power electronics cooling device according to claim 1.
- 20. (Currently amended) Cooling The cooling device according to claim 3, wherein the cooling circuit further comprises turbulators (32) distributed in the liquid circulation channels.
 - 21. (Canceled)
- 22. (Currently amended) Device A device for cooling power electronics (9), comprising:

a support plate (21) on which the power electronics are mounted, said support plate (21) being planar;

a first metal plate including at least two liquid circulation channels formed in said first metal plate, said at least two circulation channels extending in different directions,

wherein a cooling circuit (22) for cooling by circulation of a liquid is defined by said liquid circulation channels,

wherein a plurality of deflectors are placed in the cooling circuit in order to guide the

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circulation of the liquid, and

wherein turbulators are configured in the cooling circuit in a junction of said twoliquid circulations channels placed in the cooling circuit in order to accelerate the circulation
of the liquid, said turbulators being distributed between two deflectors along a fluid
circulation direction in the cooling circuit.

- 23. (Canceled)
- 24. (Canceled)
- 25. (New) The cooling device according to claim 1, wherein the intermediate plate is fixed directly by brazing to the support plate.
- 26. (New) The cooling device according to claim 25, wherein at least one of the intermediate plate and the support plate comprises plating by co-lamination.
- 27. (New) The cooling device according to claim 26, wherein the intermediate plate and the support plate are made of aluminum.